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TITLE: EPOXY RESIN COMPOSITION FOR SEALING SEMICONDUCTOR

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INVENTOR-INFORMATION:

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ABSTRACT:

PROBLEM TO BE SOLVED: To obtain a composition excellent in adhesion to metals and organic substrate and in resistance to solder cracking by incorporating therein an epoxy resin, a phenolic resin curing agent, a curing accelerator, a inorganic filler, and an epoxy-silane coupling agent having a specific silanol group.

SOLUTION: The epoxy coupling agent is a compound as illustrated by the formula. In the formula, R is -CH<sub>3</sub> or -C<sub>2</sub>H<sub>5</sub>; a+b+c=3; a>0; b>0; c>0; b/(b+c)>0.6. The epoxy resin represents all of monomers, oligomers and polymers having epoxy groups. It desirably includes epoxy resins of biphenyl-type, triphenylmethane-type, stilbene-type, etc. The phenolic resin curing agent desirably includes phenolic novolak resins, xylylene-modified phenolic resins, etc. As the curing accelerator, 1,8-diazabicyclo(5.4.0)undecene-7, triphenylphosphine, etc., are preferred. Preferable inorganic fillers include globular fused silica.

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